

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB020N08N5	**Issued**	11. May 2022
MA#	MA005707109		
Package	PG-TO263-3-2	**Weight***	1563.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.308	0.34	0.34	3394	3394
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.44	19.47	194421	194674
wire	non noble metal	aluminium	7429-90-5	13.501	0.86	0.86	8634	8634
encapsulation	inorganic material	zincoxide	1314-13-2	6.775	0.43		4333	
	miscellaneous	miscellaneous	-	27.101	1.73		17331	
	plastics	epoxy resin	-	101.627	6.50		64989	
	inorganic material	silicondioxide	60676-86-0	542.012	34.66	43.32	346610	433263
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6175	6175
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.095	0.01		61	
	noble metal	silver	7440-22-4	0.119	0.01		76	
	non noble metal	lead	7439-92-1	4.528	0.29	0.31	2895	3032
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.02	35.07	350225	350681
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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